## W2012 SERIES

#### 1. PART NO. EXPRESSION :

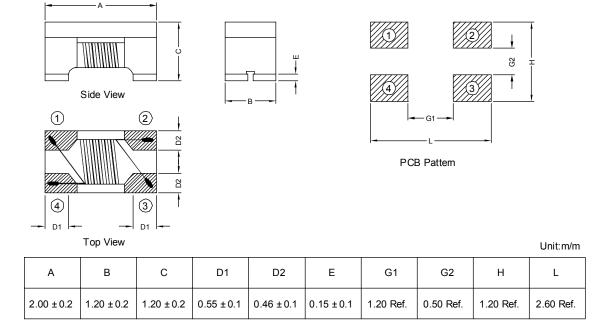
<u>W</u> 2	2012	<u>2 F (</u>	<u>670</u>	- <u>R D</u> -	
(a)	(b)	(C)	(d)	(e)(f)	(g)

- (a) Series code
- (b) Dimension code

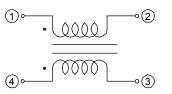
(c) Material code

- (d) Impedance code :  $670 = 67\Omega$
- (e) R : Tape & Reel
- (f) Rated Current : D = 400mA
- (g) 10: Standard
  - 11 ~ 99 : Internal control number

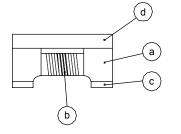
#### 2. CONFIGURATION & DIMENSIONS :



#### 3. SCHEMATIC :



### 4. MATERIALS :



(b) Wire

(a) Core

(c) Terminal



**RoHS** Compliant

NOTE : Specifications subject to change without notice. Please check our website for latest information.

20.05.2014

## W2012 SERIES

### 5. GENERAL SPECIFICATION :

a) Operating temp. : -40° C to 125° C

b) Storage condition (component in its packaging)

i) Temperature : -10 to 40° C

ii) Humidity: 60%

### 6. ELECTRICAL CHARACTERISTICS :

Part No.	Common mode Impedance (Ω)	Test Frequency (MHz)	DCR (Ω) Max.	Rated Current (mA)	Rated Voltage (Vdc)	Withstand Voltage (Vdc)	IR (Ω) Min.
W2012F500-RD-10	50 ± 25%	100	0.25	400	50	125	100M
W2012F670-RD-10	67 ± 25%	100	0.30	400	50	125	100M
W2012F900-RD-10	90 ± 25%	100	0.30	400	50	125	100M

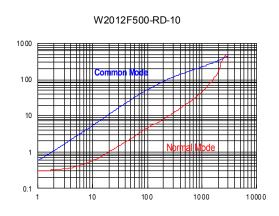


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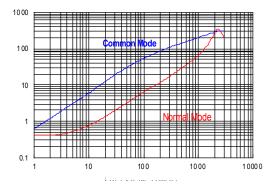
20.05.2014

### W2012 SERIES

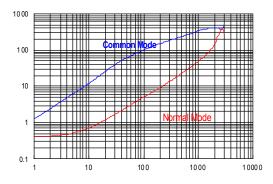
7. CHARACTERISTICS CURVES :



W2012F670-RD-10



W2012F900-RD-10



SUPERWORLD ELECTRONICS (S) PTE LTD

Pb RoHS Compliant

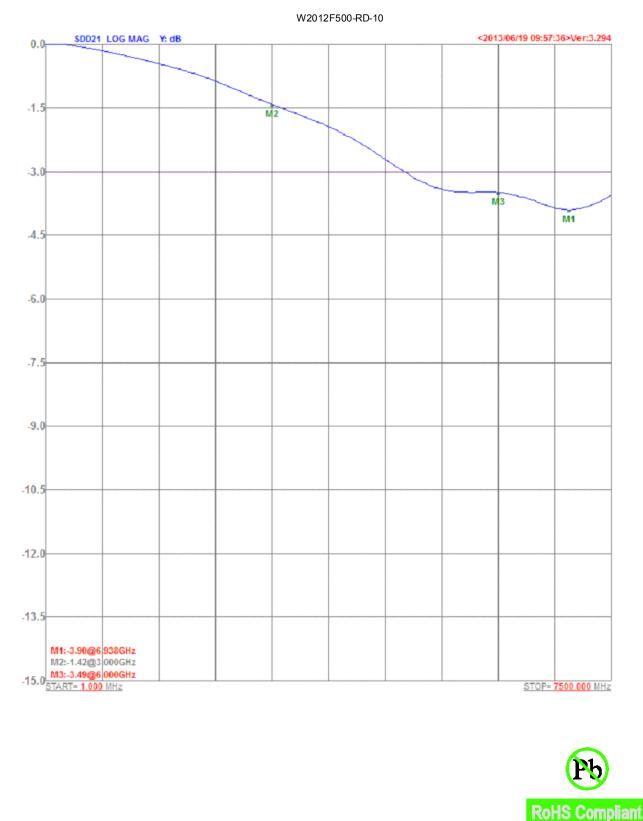
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PG. 3

W2012 SERIES

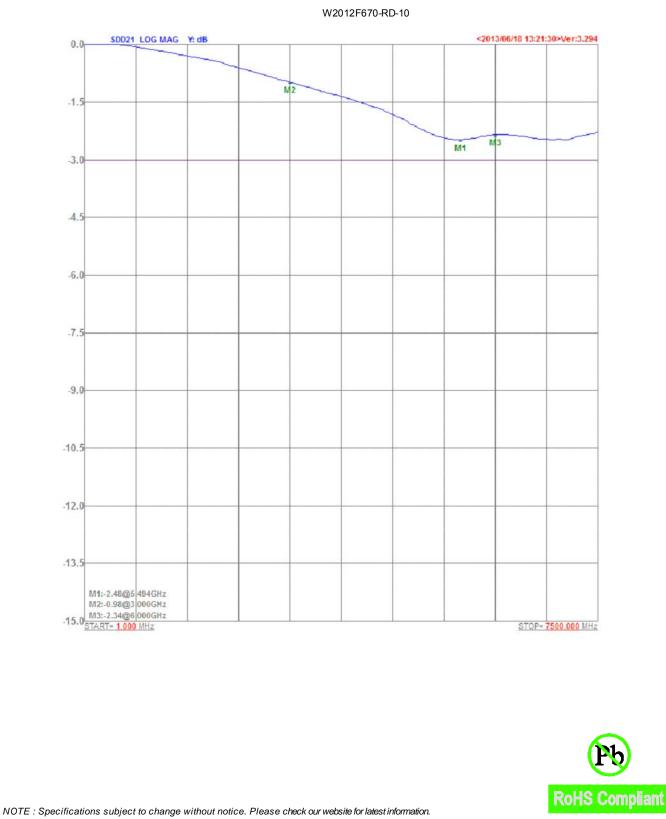
7.1 Insertion Loss Test



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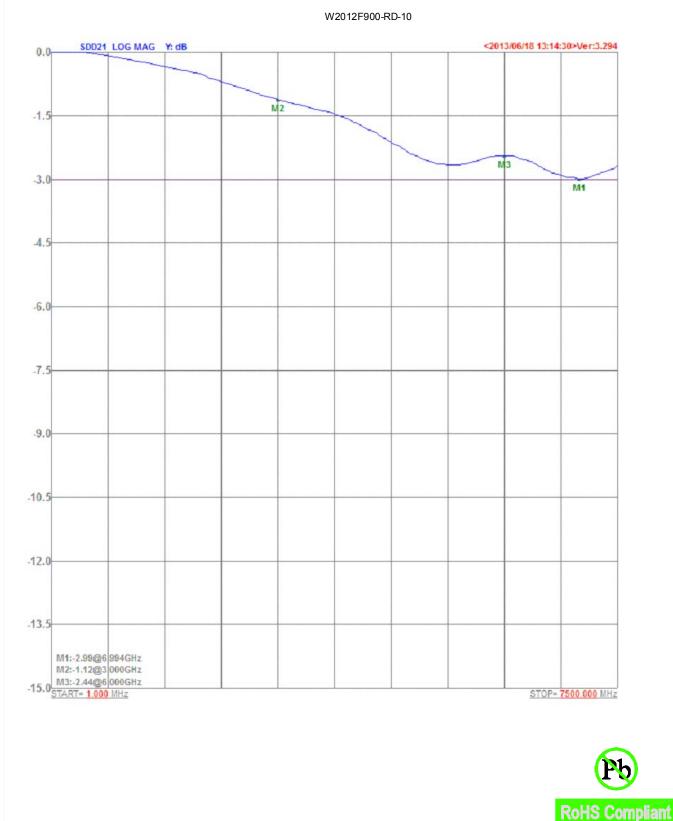
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W2012 SERIES



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### W2012 SERIES

#### 8. SOLDERING AND MOUNTING :

#### 8-1. Soldering

Mildly activated rosin fluxes are preferred. Our terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

#### 8-1.1 Solder Re-flow :

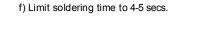
Recommended temperature profiles for re-flow soldering in Figure 1.

#### 8-1.2 Soldering Iron (Figure 2):

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note :

- a) Preheat circuit and products to 150° C.
- b) 355° C tip temperature (max)
- c) Never contact the ceramic with the iron tip



d) 1.0mm tip diameter (max)

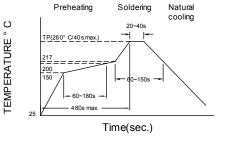
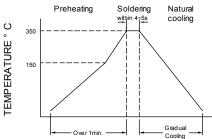


Figure 1. Re-flow Soldering : 3 times max.



e) Use a 20 watt soldering iron with tip diameter of 1.0mm

Figure 2. Iron Soldering times: 1 times max.



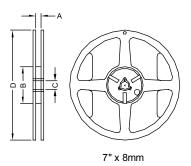
NOTE : Specifications subject to change without notice. Please check our website for latest information.

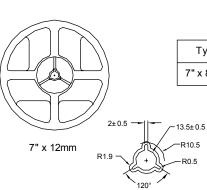
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### W2012 SERIES

#### 9. PACKAGING INFORMATION :

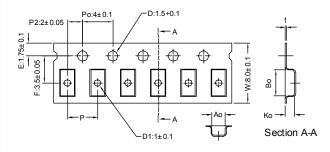
#### 9-1. Reel Dimension





Туре	A(mm)	B(mm)	C(mm)	D(mm)
7" x 8mm	9.0±0.5	60.0±2.0	13.5±0.5	178.0±2.0

### 9-2 Tape Dimension / 8mm



Series	Ao(mm)	Bo(mm)	Ko(mm)	P(mm)	t(mm)
W2012	1.50± 0.10	2.25± 0.10	1.35± 0.10	4.0±0.1	0.22± 0.05

#### 9-3. Packing Quantity

Series	W2012	
Chip / Reel	2000	
Inner Box	10000	
Middle Box	50000	
Carton	100000	

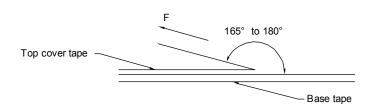


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20.05.2014

### W2012 SERIES

#### 9-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp.	Room Humidity	Room atm	Tearing Speed
(° C)	(%)	(hPa)	(mm/min)
5~35	45~85	860~1060	

### **Application Notice**

#### 1. Storage Conditions :

- To maintain the solderability of terminal electrodes :
  - a) Recommended products should be used within 12 months from the time of delivery.
  - b) The packaging material should be kept where no chlorine or sulfur exists in the air.

#### 2. Transportation :

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) The use of tweezers or vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.



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20.05.2014